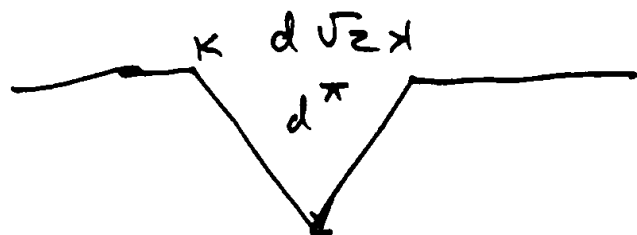
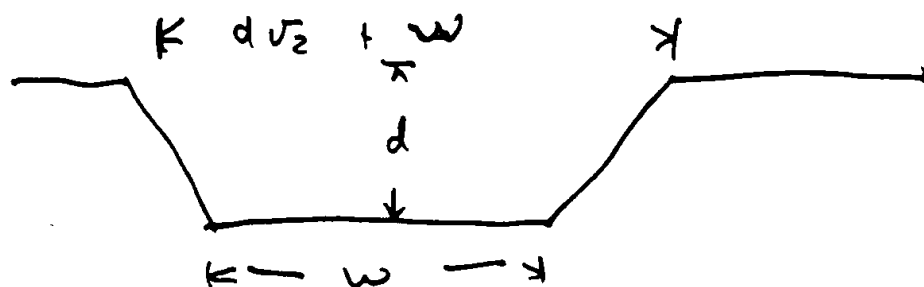


**NORTHRUP EXHIBIT N**



Scribe line  $\approx$  70% thickness



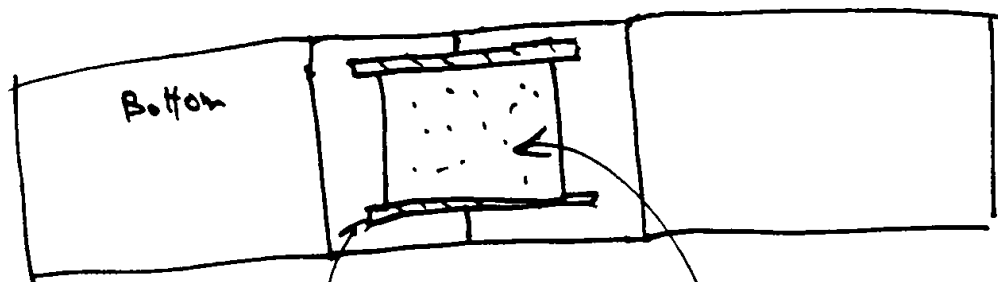
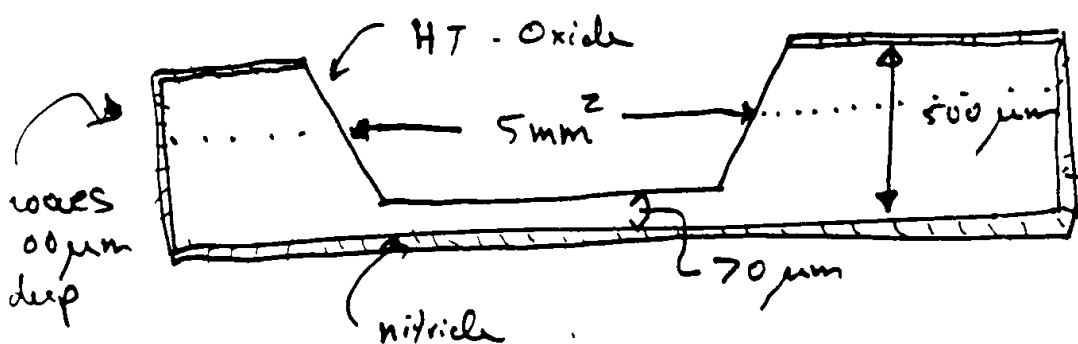
or

Syringe - U. groove



M. All 

B) Summary of recent design meeting  
with Courtney and Jim on



Bond pads polyheater/poly silicon

Processing Steps:

- 1) RCA Clean
- 2) Tunnel oxide
- 3) Poly silicon dep.
- 4) Dope poly (phos) dep. have
- 5) dep. SiN
- 6) Pattern well-side
  - 1) wells
  - 2) V-grooves
  - 3) Scribe lines
- 7) Plasma etch
- 8) KOH - timed etch
- 9) Strip SiN
- 10) Strip oxide